

产品规格书

Specification of products

产品名称: 快恢复二极管

产品型号: MFDK200U18NACK8

浙江世菱半导体有限公司
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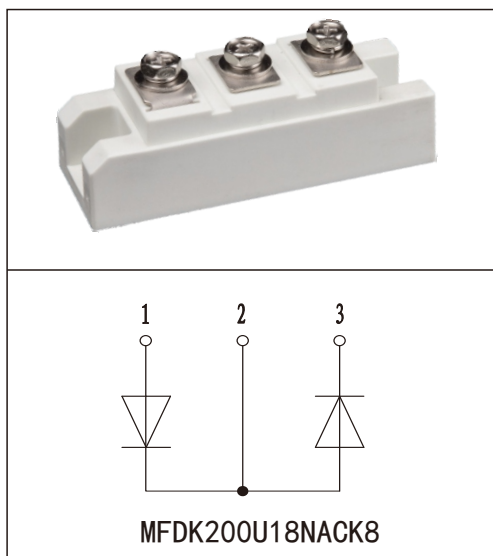
拟制	审核	核准
林益龙	曹剑龙	宗瑞

PRODUCT FEATURES

- Ultrafast Reverse Recovery Time
- Soft Reverse Recovery Characteristics
- Low Reverse Recovery Loss
- Low Forward Voltage
- High Surge Current Capability
- Low Inductance Package

APPLICATIONS

- Inversion Welder
- Uninterruptible Power Supply (UPS)
- Plating Power Supply
- Ultrasonic Cleaner and Welder
- Converter & Chopper
- Power Factor Correction (PFC) Circuit



ABSOLUTE MAXIMUM RATINGS

$T_C=25^{\circ}\text{C}$ unless otherwise specied

Symbol	Parameter	Test Conditions	Values	Unit
V_R	Maximum D.C. Reverse Voltage		1800	V
V_{RRM}	Maximum Repetitive Reverse Voltage		1800	V
$I_{F(AV)}$	Average Forward Current	$T_C=110^{\circ}\text{C}$, Per Diode	200	A
		$T_C=120^{\circ}\text{C}$, 20KHz, Per Moudle	150	A
$I_{F(RMS)}$	RMS Forward Current	$T_C=110^{\circ}\text{C}$, Per Diode	280	A
I_{FSM}	Non-Repetitive Surge Forward Current	$T_J=45^{\circ}\text{C}$, $t=10\text{ms}$, 50Hz, Sine	1400	A
		$T_J=45^{\circ}\text{C}$, $t=8.3\text{ms}$, 60Hz, Sine	1650	A
I^2t	I^2t (For Fusing)	$T_J=45^{\circ}\text{C}$, $t=10\text{ms}$, 50Hz, Sine	16450	A^2s
		$T_J=45^{\circ}\text{C}$, $t=8.3\text{ms}$, 60Hz, Sine	19612	A^2s
P_D	Power Dissipation		568	W
T_J	Junction Temperature		-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range		-40 to +125	$^{\circ}\text{C}$
V_{isol}	Insulation Test Voltage	AC, $t=1\text{min}$	3000	V
Torque	Module-to-Sink	Recommended (M6)	3~5	N.M
Torque	Module Electrodes	Recommended (M6)	3~5	N.M
$R_{\theta JC}$	Thermal Resistance	Junction-to-Case	0.14	$^{\circ}\text{C} / \text{W}$
Weight			160	g

ELECTRICAL CHARACTERISTICS

$T_C=25^\circ\text{C}$ unless otherwise specied

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{RM}	Reverse Leakage Current	$V_R=1800V$	--	--	5	mA
		$V_R=1800V, J=125^\circ\text{C}$	--	--	20	mA
V_F	Forward Voltage	$I_F=200A$	--	2.0	2.1	V
		$I_F=200A, T_J=125^\circ\text{C}$	--	1.8	1.85	V
t_{rr}	Reverse Recovery Time	$I_F=1A, V_R=30V, di_F/dt=-200A/\mu s$	--	180	--	ns
t_{rr}	Reverse Recovery Time	$V_R=900V, I_F=200A$	--	220	--	ns
I_{RRM}	Max. Reverse Recovery Current	$di_F/dt=-200A/\mu s, T_J=25^\circ\text{C}$	--	10	--	A
t_{rr}	Reverse Recovery Time	$V_R=900V, I_F=200A$	--	850	--	ns
I_{RRM}	Max. Reverse Recovery Current	$di_F/dt=-200A/\mu s, T_J=125^\circ\text{C}$	--	25	--	A

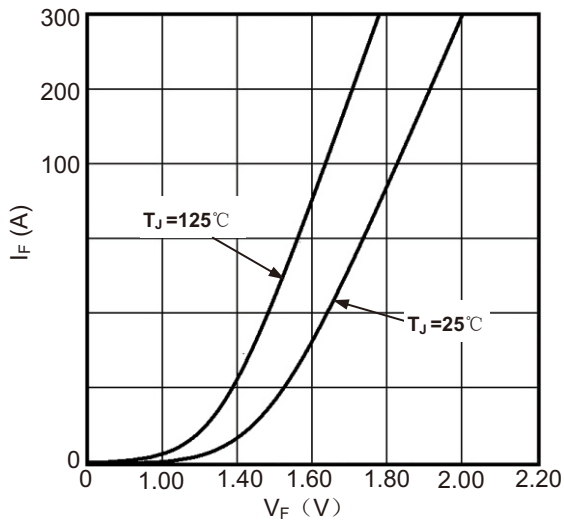


Figure1. Forward Voltage Drop vs Forward Current

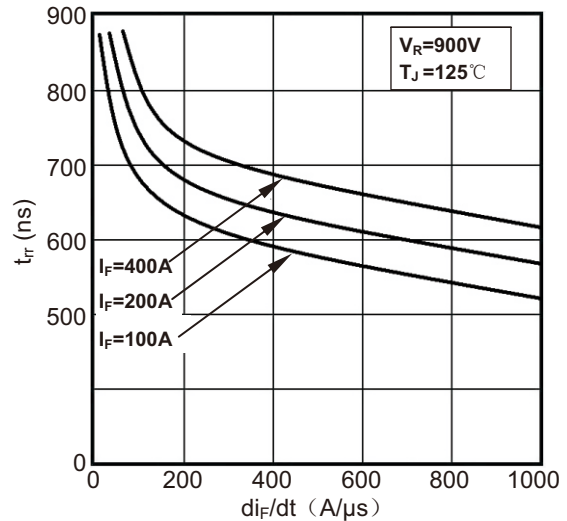


Figure2. Reverse Recovery Time vs di_F/dt

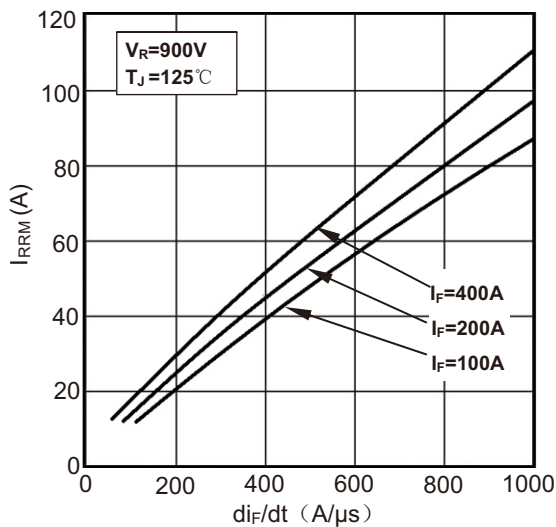


Figure3. Reverse Recovery Current vs di_F/dt

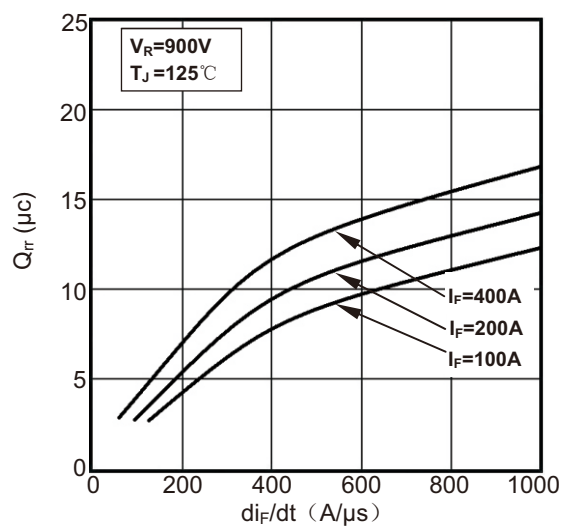


Figure4. Reverse Recovery Charge vs di_F/dt

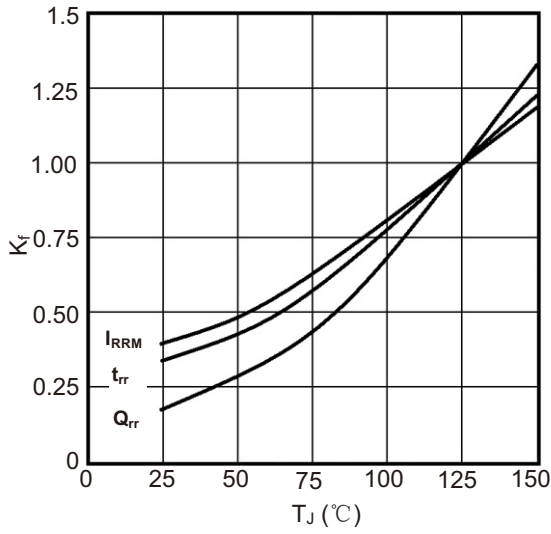


Figure5. Dynamic Parameters vs Junction Temperature

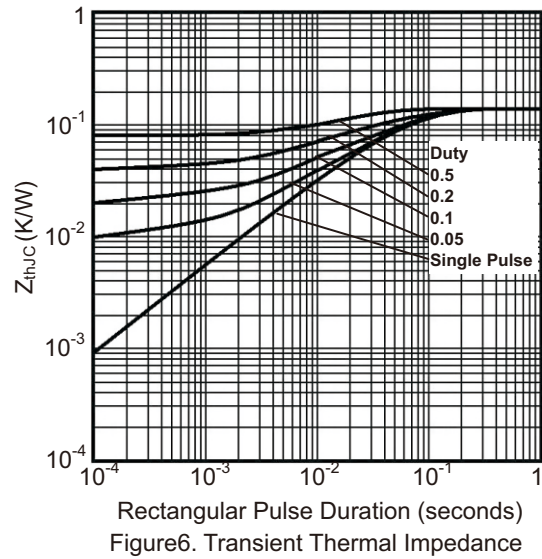
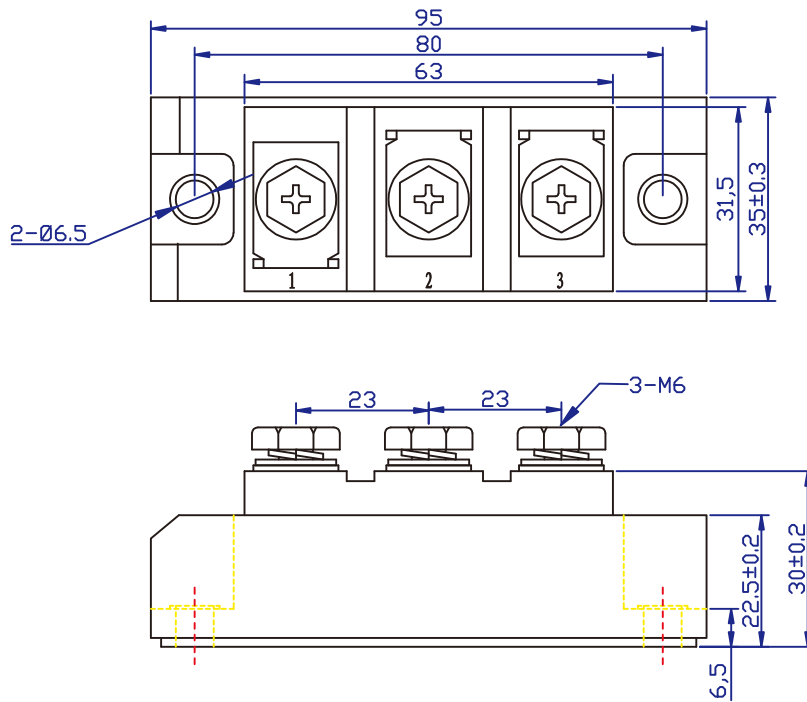


Figure6. Transient Thermal Impedance

Package Outlines



Unit:mm